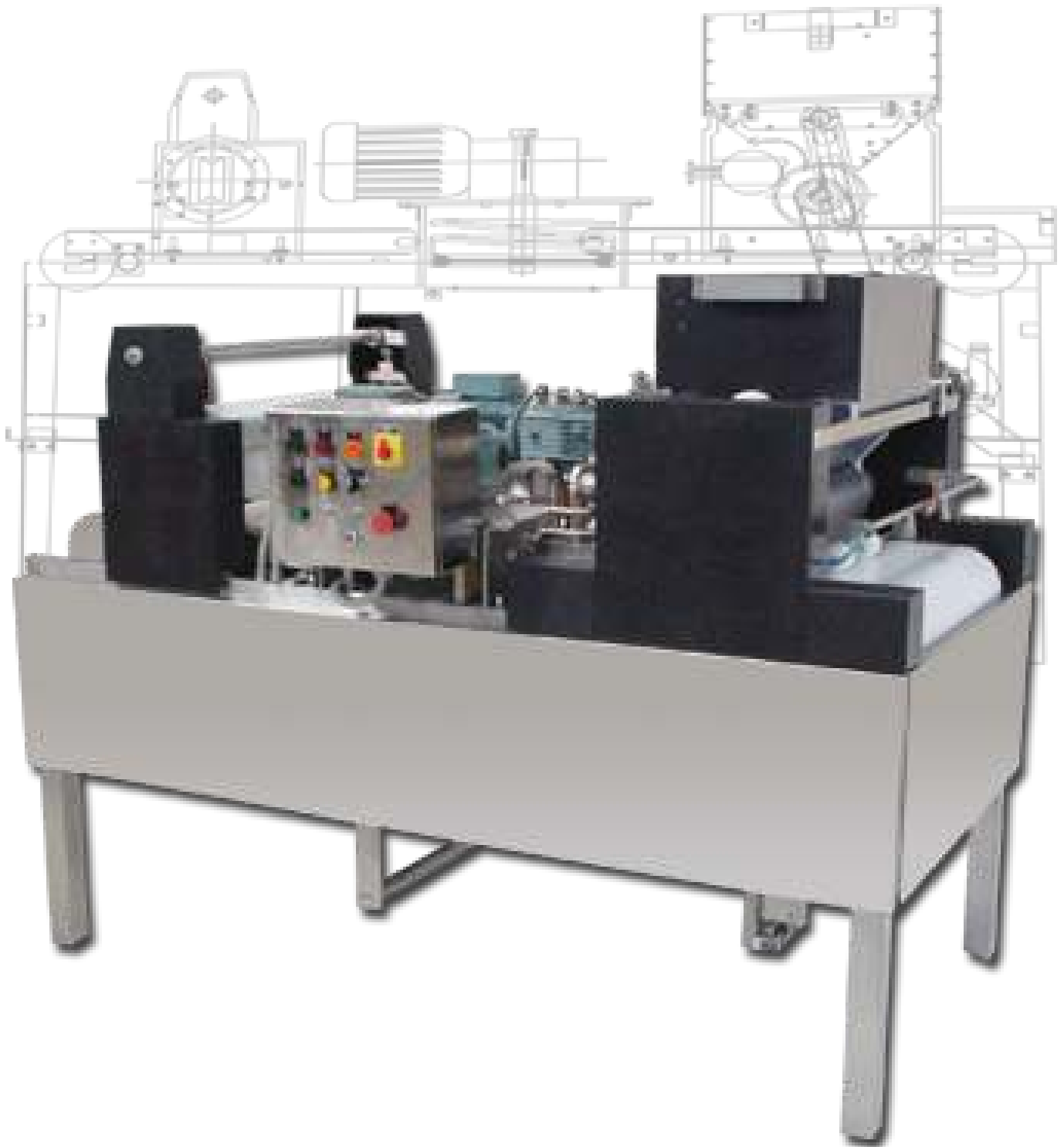


Automatic Wafer Spreading Machine
Contact Wafer Sheet Creaming
“CR6” Series



Better by Design.....



Spreading machines spread an exact amount of fat cream onto the wafer sheets and automatically stack the requested number of spread sheets together with the uncreamed top sheet into a wafer block. A thermostat allows to heat the cream spreading roller as well as the counter-roller up to an exact temperature. The speed of the two rollers and of the spreading belt can be steplessly adjusted independently of each other.

The desired thickness of the individual cream layers is obtained by regulating the speed and the distance between the rollers. It prevents the cream from being spread in front of the wafer(cream wedge), which allows efficient spreading of cream.

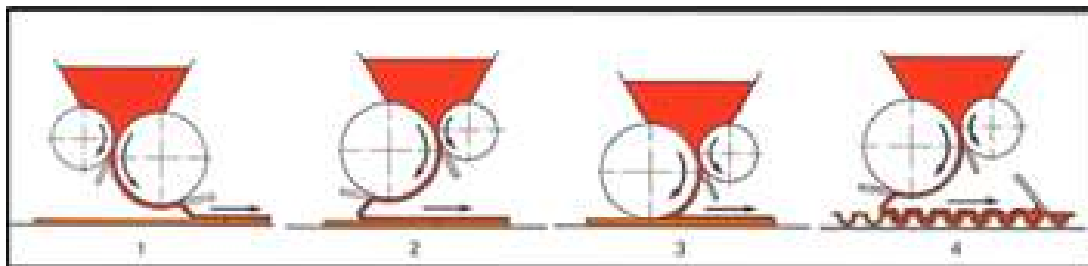
A paddle in the cream hopper provides for uniform distribution of the cream on the spreading roller. Flexible sealing lips in the cream hopper prevent leakage of liquid creams when the machines is out of operation.

The uncreamed top sheet passes the spreading roller without contact due to cam-controlled lowering of the spreading table. After spreading wafer blocks are formed out of two to seven wafer sheets with the spiral stacker. There the wafer sheets get maximum support and are stacked. Even delicate wafer sheets with heavy creams can be processed. Exact block formation guarantees a minimum of cutting residue in the following cutting process. The requested number of cream layers is set by a selector switch and electronically controlled by light barriers

Technical Data

TYPE	CR6-1	CR6-2
Spreading system	Contact spreading system	
Wafer sheet dimensions (mm)	290X460	350X500
Width of spreading roller	462mm	462mm
Wafer sheets per minute	36-40 (max)	36-40 (max)
Electrical load (Kw)	3.5	5
Dimensions		
Length	1950	2700
Width	1250	1250
Height	1550	1550
Weight (approx.kg)net weight incl.seaworthy packing	700 900	700 1200
Shipping space (apprx.m3)	4.0	4.0

Wafer Creaming Methods



1. Film method 2. Reverse film method 3. Contact method 4. Film method for hallow wafers

***Modifications Reserved**

We are constantly guided by our principle of offering our customers better and better machines; to give increased efficiency and higher levels of automation. The technical data and illustrations are subject to change without notice

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